

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
 (Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
P-US058-A-MF

Re Application Of: **Hai Hong**

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/763,594	January 22, 2004	Wollschlager, Jeffrey M.	32107	1732	

Title: **Silicone Compositions, Methods of Making, and Uses Thereof**

Address to:
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

37 CFR 1.97(b)

1. ☐ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

37 CFR 1.97(c)

2. ☒ The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

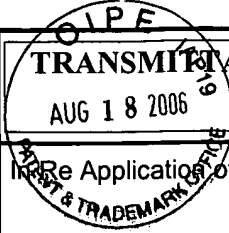
☐ the statement specified in 37 CFR 1.97(e);

OR

☒ the fee set forth in 37 CFR 1.17(p).

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<div style="display: flex; justify-content: space-between; align-items: center;"> <div style="text-align: left;">  </div> <div> TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT (Under 37 CFR 1.97(b) or 1.97(c)) </div> </div>				Docket No. P-US058-A-MF	
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Payment of Fee
 (Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

☐ A check in the amount of _____ is attached.

☒ The Director is hereby authorized to charge and credit Deposit Account No. 502123
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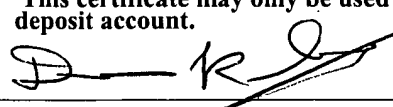
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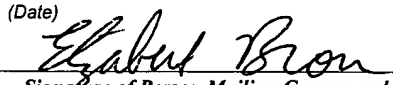


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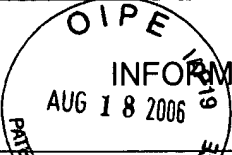

 Signature of Person Mailing Correspondence

Elizabeth Brown

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Dated: August 14, 2006

CC:

	ATTY DOCKET NO. P-US058-A-MF	APPLICATION NO. 10/763,594
	APPLICANT(S) Hai Hong	
	FILING DATE January 22, 2004	GROUP ART UNIT 1732

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	3,598,467	08/10/1971	Durk Jon Pearson	350	3.5	
	3,600,249	08/17/1971	Jackson, et al.	156	197	
	3,697,630	10/10/1972	Stanley Y. Yoshino	264	28	
	5,190,637	03/02/1993	Henry Guckel	205	118	
	5,580,699	12/03/1996	Layman, et al.	430	311	
	6,022,668	02/08/2000	Burberry, et al.	430	302	
	6,027,630	02/22/2000	Adam L. Cohen	205	135	
	6,107,001	08/22/2000	Lewis, et al.	430	302	
	6,145,565	11/14/2000	Fromson, et al.	156	580	
	6,354,701	03/12/2002	Aharon Korem	347	106	
	6,378,273	04/30/2002	Trani, et al.	53	450	
	7,070,903	07/04/2006	Suda, et al.	430	270.1	

U.S. PATENT APPLICATION PUBLICATIONS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	2002/0100256	08/01/2002	Trani, et al.	53	452	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	Cohen, et al., "EFAB: Batch Production of Functional, Fully-Dense Metal Parts with Micron-Scale Features", Proc. 9th Solid Freeform Fabrication, The University of Texas at Austin, August 1998, pg. 161.
	Adam L. Cohen, et al., "EFAB: Rapid, Low-Cost Desktop Micromachining of High Aspect Ratio True 3-D MEMS", Proc. 12th IEEE Micro Electro Mechanical Systems Workshop, IEEE, Jan 1999, pg. 244.
	"Microfabrication - Rapid Prototyping's Killer Application", Rapid Prototyping Report, CAD/CAM Publishing, Inc., June 1999, pgs. 1-5.
	Adam L. Cohen, "3-D Micromachining by Electrochemical Fabrication", Micromachine Devices, March 1999, pgs. 6-7.
	Gang Zhang, et al., "EFAB: Rapid Desktop Manufacturing of True 3-D Microstructures", Proc. 2nd International Conference on Integrated MicroNanotechnology for Space Applications, The Aerospace Co., April 1999.
	F. Tseng, et al., "EFAB: High Aspect Ratio, Arbitrary 3-D Metal Microstructures Using a Low-Cost Automated Batch Process", 3rd International Workshop on High Aspect Ratio Microstructure Technology (HARMST'99), June 1999.
	Adam L. Cohen, et al., "EFAB: Low-Cost, Automated Electrochemical Batch Fabrication of Arbitrary 3-D Microstructures", Micromachining and Microfabrication Process Technology, SPIE 1999 Symposium on Micromachining and Microfabrication, September 1999.

EXAMINER:	DATE CONSIDERED:
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INFORMATION DISCLOSURE CITATION	ATTY DOCKET NO. P-US058-A-MF	APPLICATION NO. 10/763,594
	APPLICANT(S) Hai Hong	
	FILING DATE January 22, 2004	GROUP ART UNIT 1732

OTHER DOCUMENTS <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>		
		F. Tseng, et al., "EFAB: High Aspect Ratio, Arbitrary 3-D Metal Microstructures Using a Low-Cost Automated Batch Process", MEMS Symposium, ASME 1999 International Mechanical Engineering Congress and Exposition, November, 1999.
		Adam L. Cohen, "Electrochemical Fabrication (EFABTM)", Chapter 19 of the MEMS Handbook, edited by Mohamed Gad-El-Hak, CRC Press, 2002, pgs. 19/1 - 19/23.

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